

1. Packaged Integrated Circuit (PIC), comprising at least one radio frequency component included in an Integrated Circuit die (ICD) being associated with a radio frequency antenna (RFA), said Integrated Circuit die (ICD) being included in said Packaged Integrated Circuit (PIC)  
**CHARACTERISED IN THAT** said radio frequency antenna is also included in said Packaged Integrated Circuit package (PIC) and is excluded from said Integrated Circuit die (ICD).

2. Packaged Integrated Circuit (PIC) according to claim 1,  
**CHARACTERISED IN THAT** said Packaged Integrated Circuit (PIC) includes an Integrated Circuit Package (ICPA) which houses said at least one radio frequency component and said radio frequency antenna (RFA) which is constituted by at least one metal object that is part of said Integrated Circuit package.

3. Packaged Integrated Circuit (PIC) according to claim 2,  
**CHARACTERISED IN THAT** said radio frequency antenna (RFA) is constituted by a wire bonding coupled to said Integrated Circuit die (ICD).

4. Packaged Integrated Circuit (PIC) according to claim 2,  
**CHARACTERISED IN THAT** said radio frequency antenna (RFA) is applied on a metal lead frame of said Integrated Circuit package (ICPA).

5. Packaged Integrated Circuit (PIC) according to claim 1,  
**CHARACTERISED IN THAT** said radio frequency antenna (RFA) consists of at least one planar metal pattern separated from a grounded metal plane by an insulating layer.

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6. Packaged Integrated Circuit (PIC) according to claim 5,  
**CHARACTERISED IN THAT** said planar metal pattern is a metal slot-pattern  
and said insulating layer is ceramic layer.

5 7. Packaged Integrated Circuit (PIC) according to claim 6,  
**CHARACTERISED IN THAT** said slot pattern consists of a first S-shaped slot.

10 8. Packaged Integrated Circuit (PIC) according to claim 7,  
**CHARACTERISED IN THAT** said radio frequency antenna (RFA) comprises a  
second S-shaped slot rotated 90 degrees with regard to said first S-shaped slot.

15 9. Packaged Integrated Circuit (PIC) according to claim 1,  
**CHARACTERISED IN THAT** said Integrated Circuit package (ICPA) is a Ball  
Grid Array package.

20 10. Packaged Integrated Circuit (PIC) according to claim 1,  
**CHARACTERISED IN THAT** said Integrated Circuit package (ICPA) is a Quad  
Flat Pack package.

25 11. Packaged Integrated Circuit (PIC) according to claim 1,  
**CHARACTERISED IN THAT** said Integrated Circuit package is a Small Outline  
package.

30 12. Radio Frequency Module including at least one Packaged  
Integrated Circuit (PIC) according to any of the claims 1 to 11.

**ABSTRACT**

~~**PACKAGED INTEGRATED CIRCUIT**~~

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Wahl

sub  
A5

add  
B2 7  
add  
C6 7